



**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**BALL GRID ARRAY SUBSTRATE HAVING WINDOW AND METHOD OF FABRICATING SAME**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Application No. \_\_\_\_\_); and

WHEREAS, Samsung Electro-Mechanics Co., Ltd, a corporation of Korea, whose post office address is 314, Maetan-3dong, Youngtong-gu, Suwon-si, Kyunggi-do 443-743, Republic of Korea (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s):

Full Name of Sole or First Assignor <b>Jong Jin LEE</b>	Assignor's Signature <i>Lee Jong Jin</i>	Date <i>March 3, 2005</i>
Address <b>314-1904, Seonbimaetul 3-Danji Apt., Songchon-dong, Daedeok-gu, Daejeon 306-777, Korea</b>		Citizenship <b>KOREA</b>

WITNESS:

I certify that I know or have satisfactory evidence that **Jong Jin LEE** is the person who appeared before me, and that he acknowledged that he signed this instrument and acknowledged it to be his free and voluntary act for the uses and purposes mentioned in the instrument.